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(54) Title: ANNULAR APODIZER FOR SMALL TARGET OVERLAY MEASUREMENT

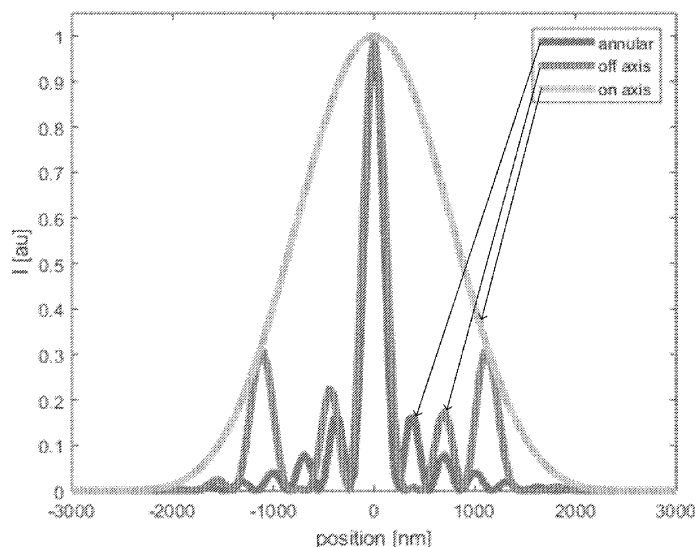


FIG. 4

(57) Abstract: Metrology is performed on a semiconductor wafer using a system with an apodizer. A spot is formed on the semiconductor wafer with a diameter from 2 nm to 5 nm. The associated beam of light has a wavelength from 400 nm to 800 nm. Small target measurement can be performed at a range of optical wavelengths.

[Continued on next page]

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